SOT1161-1

XQFN16; plastic, extremely thin quad flatpack; no leads; 16 terminals; 0.4 mm pitch; 1.8 mm x 2.6 mm x 0.50 mm body

29 September 2025

Package information



1 Package summary

Terminal position code Q (quad)
Package type descriptive code XQFN16
Package type industry code XQFN16

Package style descriptive code XQFN (extremely thin quad flatpack; no leads)

Package body material type P (plastic)

Mounting method type S (surface mount)

Issue date 29-12-2009

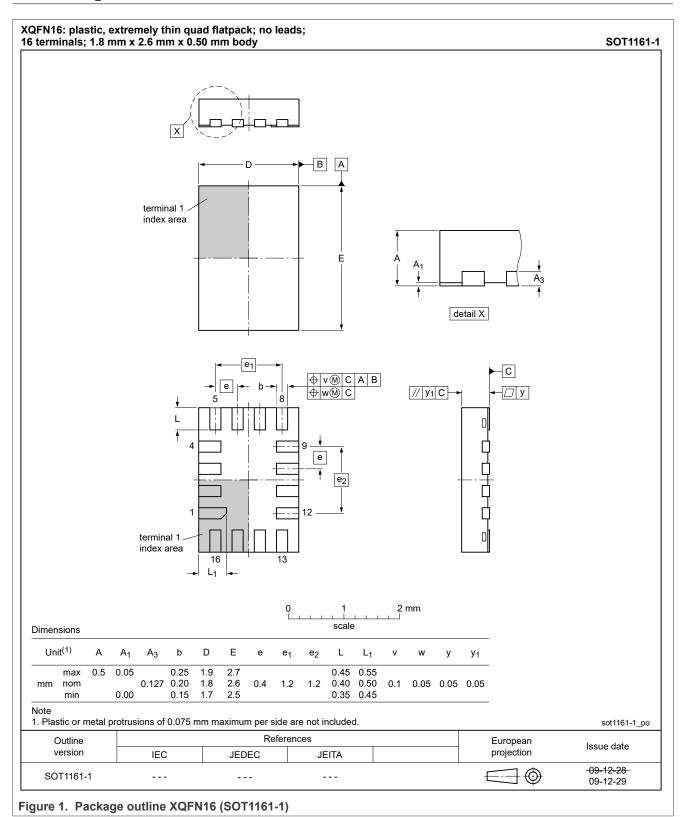
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.7	1.8	1.9	mm
package width	2.5	2.6	2.7	mm
seated height	-	-	0.5	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	16	-	



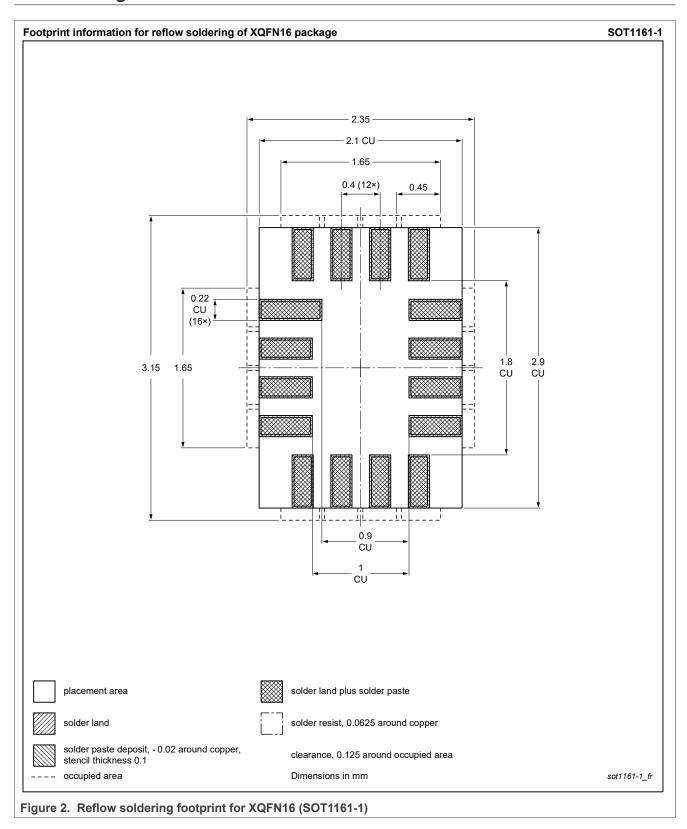
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2 Package outline



XQFN16; plastic, extremely thin quad flatpack; no leads; 16 terminals; 0.4 mm pitch; 1.8 mm x 2.6 mm x 0.50 mm body

3 Soldering



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4 Legal information

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